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Understanding [Embedded - Microprocessors](#)

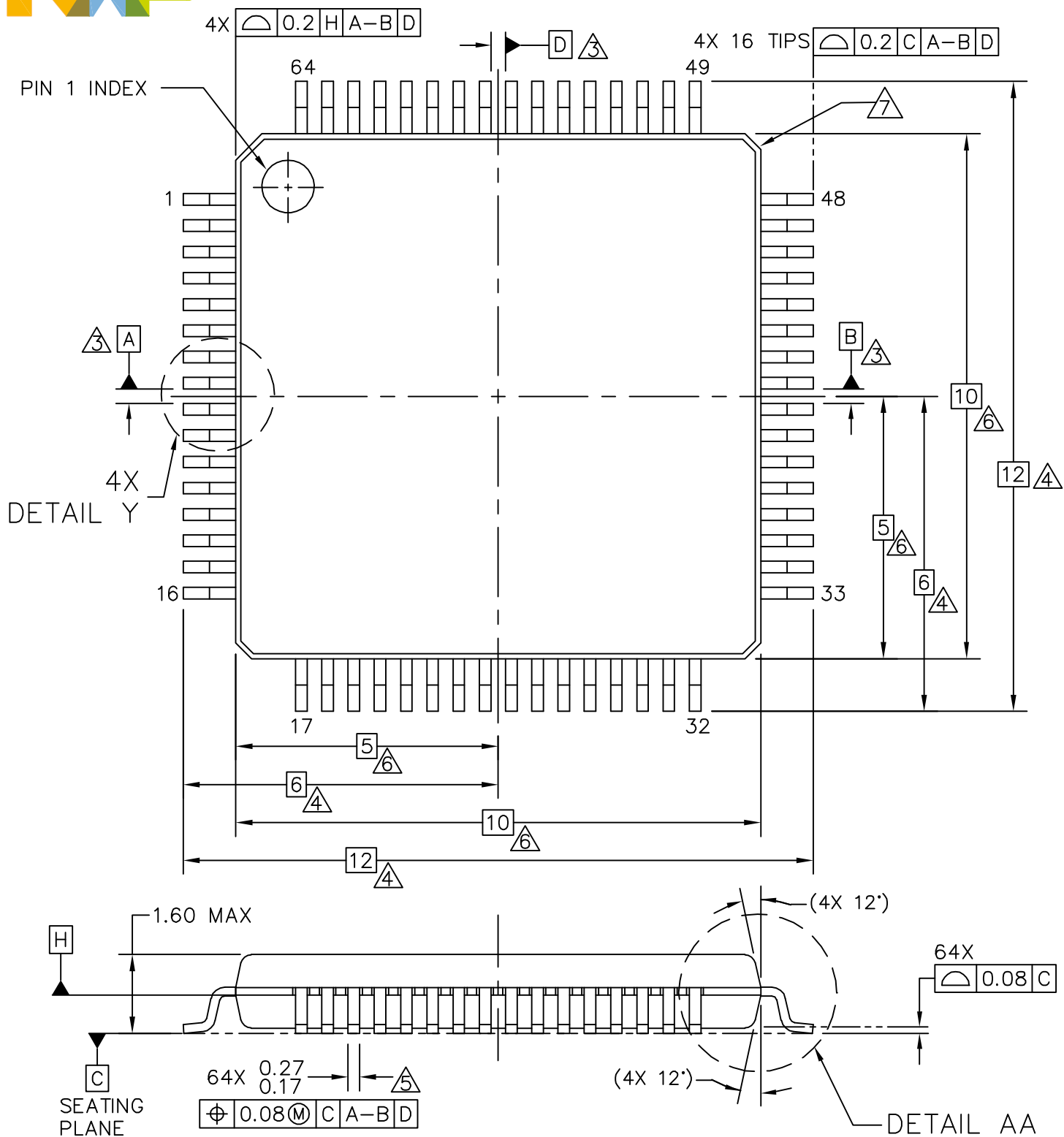
Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of [Embedded - Microprocessors](#)

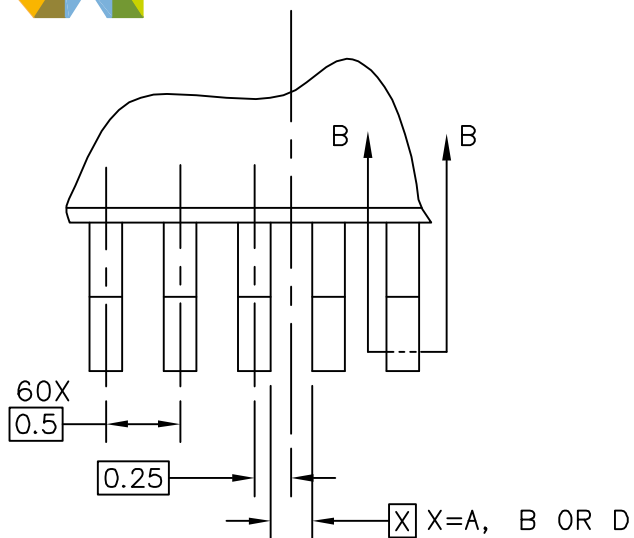
Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details

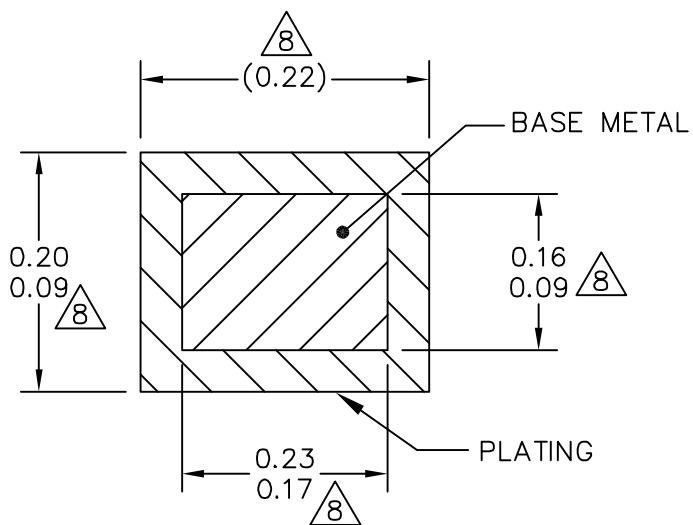
Product Status	Obsolete
Core Processor	EC000
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	10MHz
Co-Processors/DSP	-
RAM Controllers	-
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	-
SATA	-
USB	-
Voltage - I/O	3.3V, 5.0V
Operating Temperature	0°C ~ 70°C (TA)
Security Features	-
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc68sec000ae10



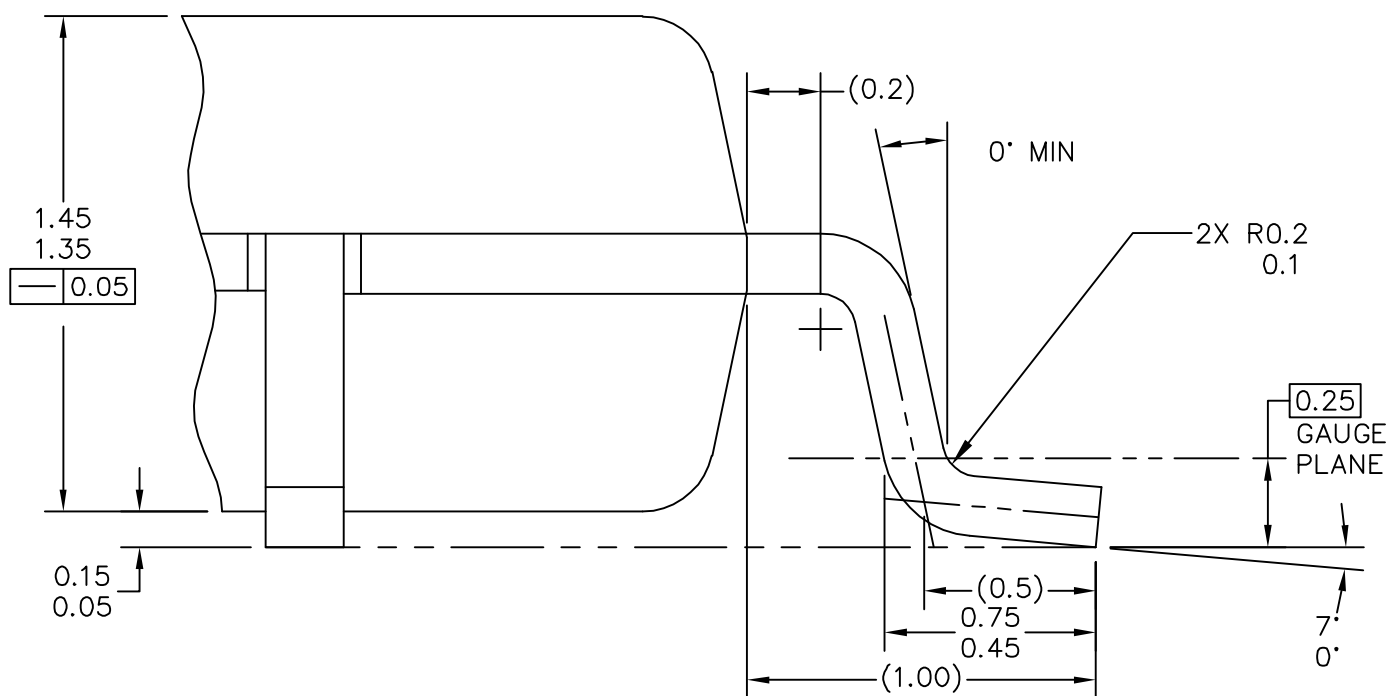
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TITLE: LQFP, 10 X 10 X 1.4 PKG, 0.5 PITCH, 64LD	DOCUMENT NO: 98ASS23234W	REV: G
	STANDARD: JEDEC MS-026 BCD	
	SOT1699-1	25 JAN 2016



DETAIL Y



SECTION B-B



DETAIL AA

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NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

△3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.

△4. DIMENSIONS TO BE DETERMINED AT SEATING PLANE C.

△5. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08 MM AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07 MM.

△6. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 MM PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSION INCLUDING MOLD MISMATCH.

△7. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

△8. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.1 MM AND 0.25 MM FROM THE LEAD TIP.

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